

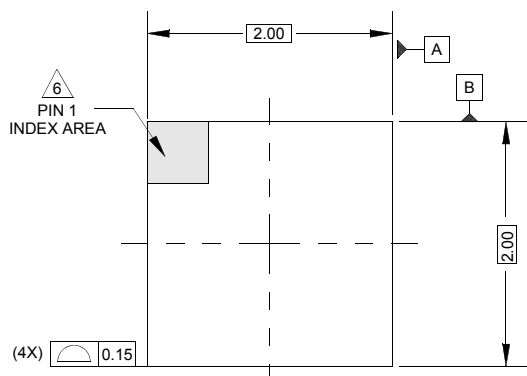
Plastic Packages for Integrated Circuits

Package Outline Drawing

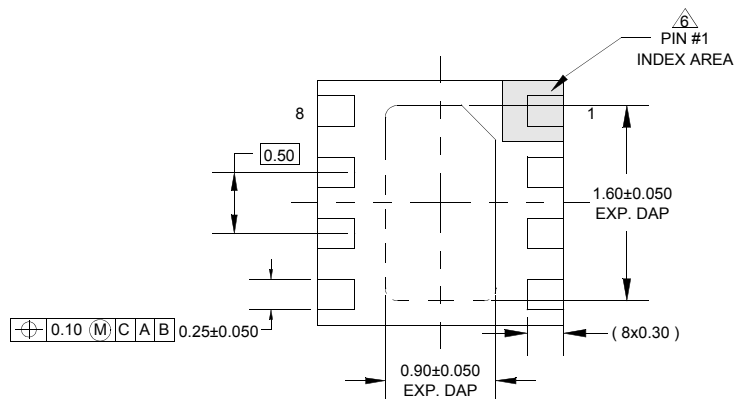
L8.2x2B

8 LEAD MICRO THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE (μ TDFN) WITH E-PAD

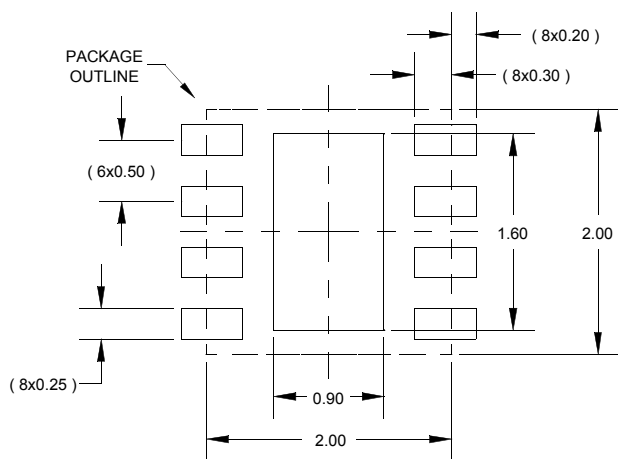
Rev 1, 5/15



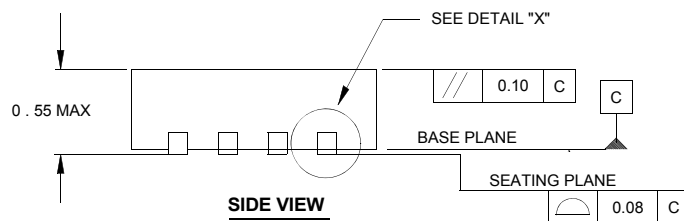
TOP VIEW



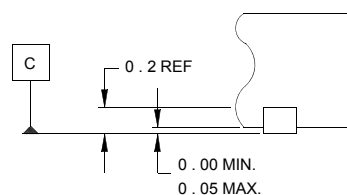
BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW



DETAIL "X"

NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
 2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
 3. Unless otherwise specified, tolerance : Decimal ± 0.05
 4. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
 5. Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.